

EDT2 IGBT and emitter controlled diode in TO247PLUS package

Features

- $V_{CE} = 750\text{ V}$
- $I_C = 200\text{ A}$
- Best-in-class highest power density, $I_C = 200\text{ A}$
- 750 V collector-emitter blocking voltage capability
- Suitable for 470 V V_{DC} systems and increase overvoltage margin for 400 V V_{DC} systems
- Very low $V_{CE(sat)}$, 1.30 V at $I_{Cnom} = 200\text{ A}$, 25°C
- Short circuit robust $t_{sc} = 5\text{ }\mu\text{s}$ at $V_{CE} = 470\text{ V}$, $V_{GE} = 15\text{ V}$
- Self limiting current under short circuit condition
- Positive thermal coefficient and very tight parameter distribution for easy paralleling
- A Reduced number of parallel devices is required due to $I_{nom} = 200\text{ A}$
- Excellent current sharing in parallel operation
- Smooth switching characteristics, low EMI signature
- Low gate charge Q_G
- Simple gate drive design
- Co-packed with fast soft recovery emitter controlled 3 diode
- TO247PLUS package with high creepage distance
- High reliability

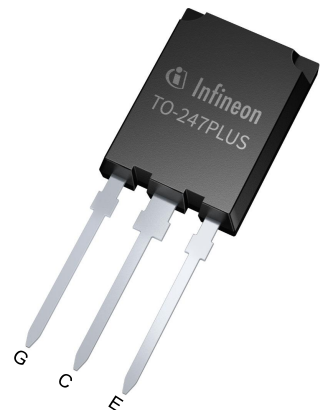
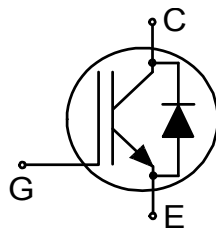
Potential applications

- xEV Inverter
- DC-link discharge switch
- Automotive aux-drives

Product validation

- Qualified for automotive applications
- Qualified according to AEC-Q101

Description



Type	Package	Marking
AIKQ200N75CP2	PG-TO247PLUS-3	AKQ20FCP

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1 Package

Table 1 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Internal emitter inductance measured 5 mm (0.197 in) from case	L_E			13.0		nH
Storage temperature	T_{stg}		-55		150	°C
Soldering temperature		wave soldering 1.6 mm (0.063 in.) from case for 10 s			260	°C
Thermal resistance, junction-ambient	$R_{th(j-a)}$				40	K/W

2 IGBT

Table 2 Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit
Collector-emitter voltage	V_{CE}		750	V
DC collector current, limited by T_{vjmax}	I_C	$T_c = 25\text{ °C}$	200	A
		$T_c = 100\text{ °C}$	200	
Pulsed collector current, t_p limited by T_{vjmax}	I_{Cpulse}		600	A
Turn-off safe operating area		$V_{CE} \leq 750\text{ V}$, $t_p = 1\text{ }\mu\text{s}$, $T_{vj} \leq 175\text{ °C}$	600	A
Gate-emitter voltage	V_{GE}		± 20	V
Transient gate-emitter voltage	V_{GE}	$t_p < 0.1\text{ }\mu\text{s}$, $D < 0.01$	± 30	V
Short-circuit withstand time	t_{SC}	$V_{CC} \leq 470\text{ V}$, $V_{GE} = 15\text{ V}$, Allowed number of short circuits < 1000 , Time between short circuits $\geq 1.0\text{ s}$, $T_{vj} = 25\text{ °C}$	5	μs
Power dissipation	P_{tot}	$T_c = 25\text{ °C}$	1071	W
		$T_c = 100\text{ °C}$	535	

Table 3 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Collector-emitter saturation voltage	V_{CEsat}	$I_C = 200\text{ A}$, $V_{GE} = 15\text{ V}$	$T_{vj} = 25\text{ °C}$	1.3	1.5	V
			$T_{vj} = 175\text{ °C}$	1.6		
Gate-emitter threshold voltage	V_{GEth}	$I_C = 2.6\text{ mA}$, $V_{CE} = V_{GE}$, $T_{vj} = 25\text{ °C}$	5	5.8	6.5	V

(table continues...)

Table 3 (continued) Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Zero gate-voltage collector current	I_{CES}	$V_{CE} = 750 \text{ V}, V_{GE} = 0 \text{ V}$	$T_{vj} = 25 \text{ }^{\circ}\text{C}$			200	μA
			$T_{vj} = 175 \text{ }^{\circ}\text{C}$		6000		
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0 \text{ V}, V_{GE} = 20 \text{ V}$				100	nA
Transconductance	g_{fs}	$I_C = 200 \text{ A}, V_{CE} = 20 \text{ V}$			140		S
Short-circuit collector current	I_{SC}	$V_{CC} \leq 470 \text{ V}, V_{GE} = 15 \text{ V}, t_{SC} \leq 5 \text{ } \mu\text{s}$, Allowed number of short circuits < 1000 , Time between short circuits $\geq 1.0 \text{ s}$, $T_{vj} = 25 \text{ }^{\circ}\text{C}$			1250		A
Input capacitance	C_{ies}	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 100 \text{ kHz}$			21250		pF
Output capacitance	C_{oes}	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 100 \text{ kHz}$			535		pF
Reverse transfer capacitance	C_{res}	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 100 \text{ kHz}$			93		pF
Gate charge	Q_G	$I_C = 200 \text{ A}, V_{GE} = 15 \text{ V}, V_{CC} = 600 \text{ V}, V_{CE} = 600 \text{ V}$			1256		nC
Turn-on delay time	t_{don}	$V_{CE} = 470 \text{ V}, V_{GE} = -8/15 \text{ V}, R_{Gon} = 5 \text{ } \Omega, R_{Goff} = 5 \text{ } \Omega, L_{\sigma} = 50 \text{ nH}, C_{\sigma} = 30 \text{ pF}$	$T_{vj} = 25 \text{ }^{\circ}\text{C}, I_C = 200 \text{ A}$		89		ns
			$T_{vj} = 175 \text{ }^{\circ}\text{C}, I_C = 200 \text{ A}$		85		
Rise time (inductive load)	t_r	$V_{CE} = 470 \text{ V}, V_{GE} = -8/15 \text{ V}, R_{Gon} = 5 \text{ } \Omega, R_{Goff} = 5 \text{ } \Omega, L_{\sigma} = 50 \text{ nH}, C_{\sigma} = 30 \text{ pF}$	$T_{vj} = 25 \text{ }^{\circ}\text{C}, I_C = 200 \text{ A}$		120		ns
			$T_{vj} = 175 \text{ }^{\circ}\text{C}, I_C = 200 \text{ A}$		117		
Turn-off delay time	t_{doff}	$V_{CE} = 470 \text{ V}, V_{GE} = -8/15 \text{ V}, R_{Gon} = 5 \text{ } \Omega, R_{Goff} = 5 \text{ } \Omega, L_{\sigma} = 50 \text{ nH}, C_{\sigma} = 30 \text{ pF}$	$T_{vj} = 25 \text{ }^{\circ}\text{C}, I_C = 200 \text{ A}$		266		ns
			$T_{vj} = 175 \text{ }^{\circ}\text{C}, I_C = 200 \text{ A}$		284		
Fall time (inductive load)	t_f	$V_{CE} = 470 \text{ V}, V_{GE} = -8/15 \text{ V}, R_{Gon} = 5 \text{ } \Omega, R_{Goff} = 5 \text{ } \Omega, L_{\sigma} = 50 \text{ nH}, C_{\sigma} = 30 \text{ pF}$	$T_{vj} = 25 \text{ }^{\circ}\text{C}, I_C = 200 \text{ A}$		46		ns
			$T_{vj} = 175 \text{ }^{\circ}\text{C}, I_C = 200 \text{ A}$		60		
Turn-on energy ¹⁾	E_{on}	$V_{CE} = 470 \text{ V}, V_{GE} = -8/15 \text{ V}, R_{Gon} = 5 \text{ } \Omega, R_{Goff} = 5 \text{ } \Omega, L_{\sigma} = 50 \text{ nH}, C_{\sigma} = 30 \text{ pF}$	$T_{vj} = 25 \text{ }^{\circ}\text{C}, I_C = 200 \text{ A}$		15.3		mJ
			$T_{vj} = 175 \text{ }^{\circ}\text{C}, I_C = 200 \text{ A}$		16.3		
Turn-off energy	E_{off}	$V_{CE} = 470 \text{ V}, V_{GE} = -8/15 \text{ V}, R_{Gon} = 5 \text{ } \Omega, R_{Goff} = 5 \text{ } \Omega, L_{\sigma} = 50 \text{ nH}, C_{\sigma} = 30 \text{ pF}$	$T_{vj} = 25 \text{ }^{\circ}\text{C}, I_C = 200 \text{ A}$		7		mJ
			$T_{vj} = 175 \text{ }^{\circ}\text{C}, I_C = 200 \text{ A}$		8.1		

(table continues...)

Table 3 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Total switching energy	E_{ts}	$V_{CE} = 470 \text{ V}$, $V_{GE} = -8/15 \text{ V}$, $R_{Gon} = 5 \Omega$, $R_{Goff} = 5 \Omega$, $L_{\sigma} = 50 \text{ nH}$, $C_{\sigma} = 30 \text{ pF}$		22.3		mJ
				24.4		
IGBT thermal resistance, junction to case ²⁾	R_{thjc}			0.1	0.14	K/W
Operating junction temperature	T_{vj}		-40		175	°C

1) Includes reverse recovery losses

2) Not subject to production test - specified by simulation

3 Diode

Table 4 Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit
Diode forward current, limited by T_{vjmax}	I_F	$T_c = 25 \text{ °C}$	200	A
		$T_c = 100 \text{ °C}$	200	
Diode pulsed current, limited by T_{vjmax}	I_{Fpulse}		600	A
Power dissipation	P_{tot}	$T_c = 25 \text{ °C}$	576	W
		$T_c = 100 \text{ °C}$	288	

Table 5 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Diode forward voltage	V_F	$I_F = 200 \text{ A}$		1.8	1.95	V
				1.9		
Diode reverse recovery charge	Q_{rr}	$V_R < 470 \text{ V}$, $R_{Gon} = 4.8 \Omega$		4.7		μC
				7.5		

(table continues...)

Table 5 (continued) Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Diode peak reverse recovery current	I_{rrm}	$V_R < 470 \text{ V}$, $R_{Gon} = 4.8 \text{ } \Omega$	$T_{vj} = 25 \text{ } ^\circ\text{C}$, $I_F = 200 \text{ A}$, $-di_F/dt = 1060 \text{ A}/\mu\text{s}$		41		A
			$T_{vj} = 175 \text{ } ^\circ\text{C}$, $I_F = 200 \text{ A}$, $-di_F/dt = 1110 \text{ A}/\mu\text{s}$		56		
Reverse recovery energy	E_{rec}	$V_R < 470 \text{ V}$, $V_{GE} = -8/15 \text{ V}$, $R_{Gon} = 4.8 \text{ } \Omega$, $L_\sigma = 50 \text{ nH}$, $C_\sigma = 30 \text{ pF}$	$T_{vj} = 25 \text{ } ^\circ\text{C}$, $-di_F/dt = 1060 \text{ A}/\mu\text{s}$		1.3		mJ
			$T_{vj} = 175 \text{ } ^\circ\text{C}$, $-di_F/dt = 1110 \text{ A}/\mu\text{s}$		2.2		
Diode thermal resistance, junction to case ¹⁾	R_{thjc}				0.2	0.26	K/W
Operating junction temperature	T_{vj}			-40		175	$^\circ\text{C}$

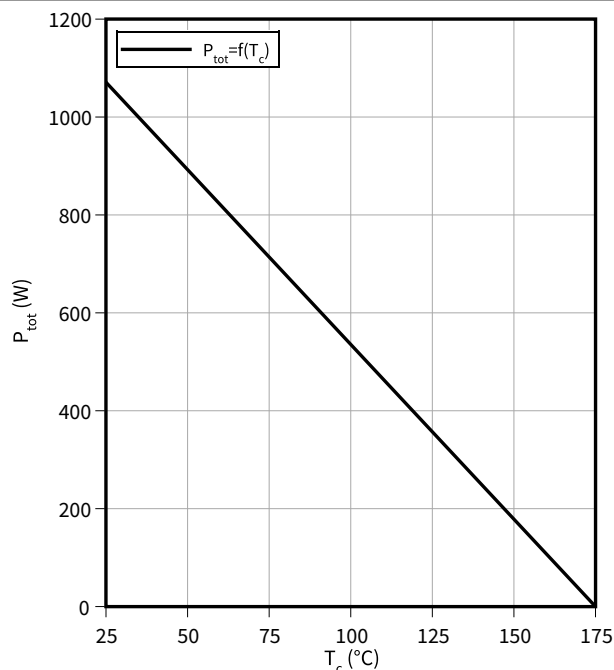
¹⁾ Not subject to test

4 Characteristics diagrams

Power dissipation as a function of case temperature, IGBT

$$P_{\text{tot}} = f(T_c)$$

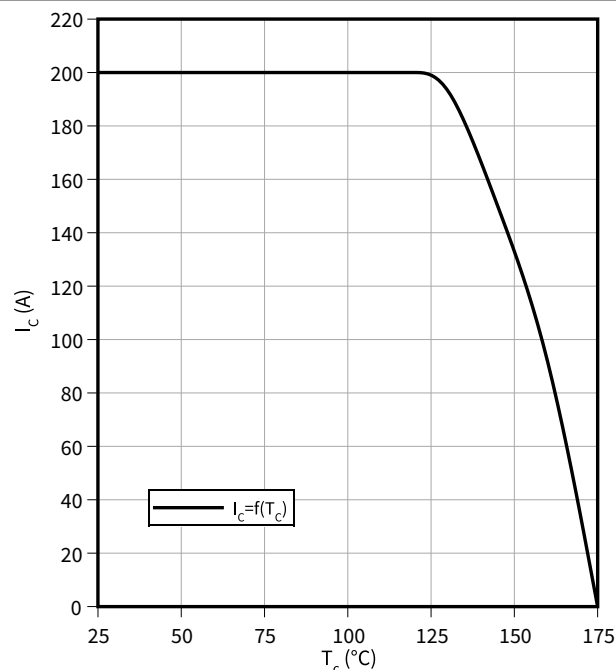
$$T_{vj} \leq 175^\circ\text{C}$$



Collector current as a function of case temperature, IGBT

$$I_c = f(T_c)$$

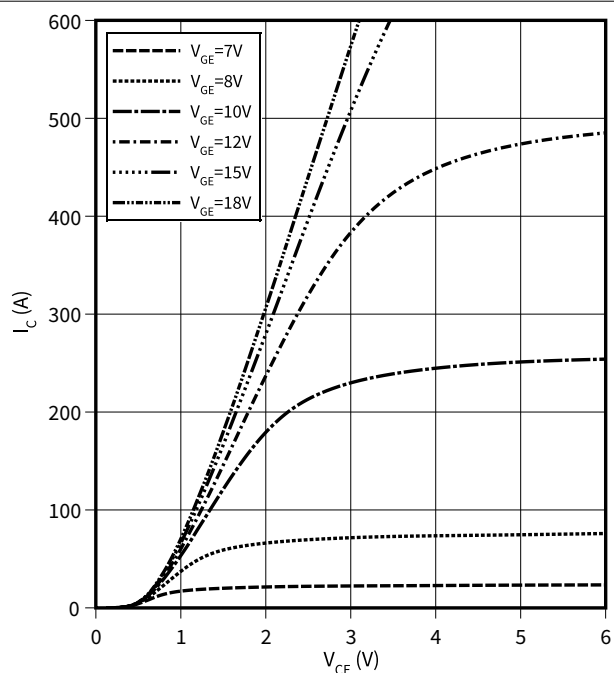
$$T_{vj} \leq 175^\circ\text{C}, V_{GE} = 15\text{ V}$$



Typical output characteristic, IGBT

$$I_c = f(V_{CE})$$

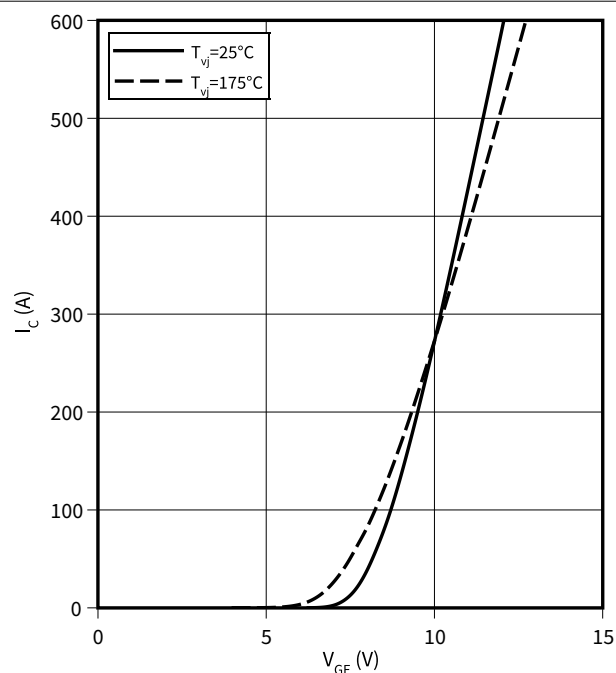
$$T_{vj} = 175^\circ\text{C}$$



Typical transfer characteristic, IGBT

$$I_c = f(V_{GE})$$

$$V_{CE} = 20\text{ V}$$

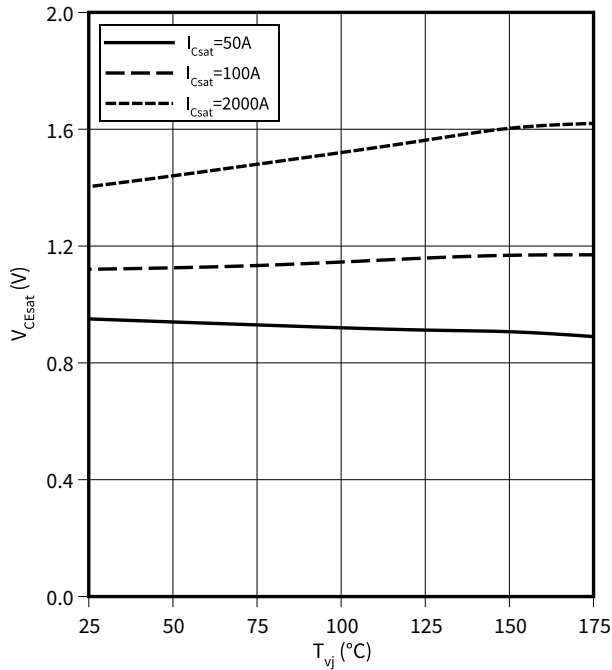


4 Characteristics diagrams

Typical collector-emitter saturation voltage as a function of junction temperature, IGBT

$$V_{CEsat} = f(T_{vj})$$

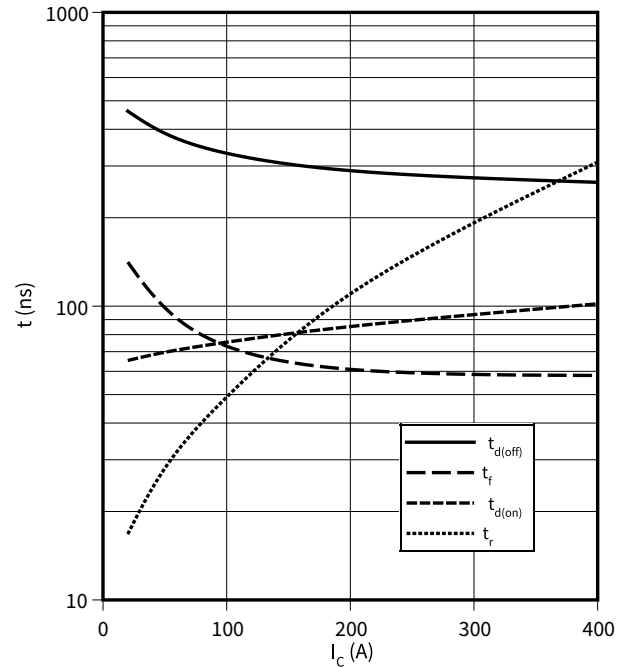
$$V_{GE} = 15 \text{ V}$$



Typical switching times as a function of collector current, IGBT

$$t = f(I_C)$$

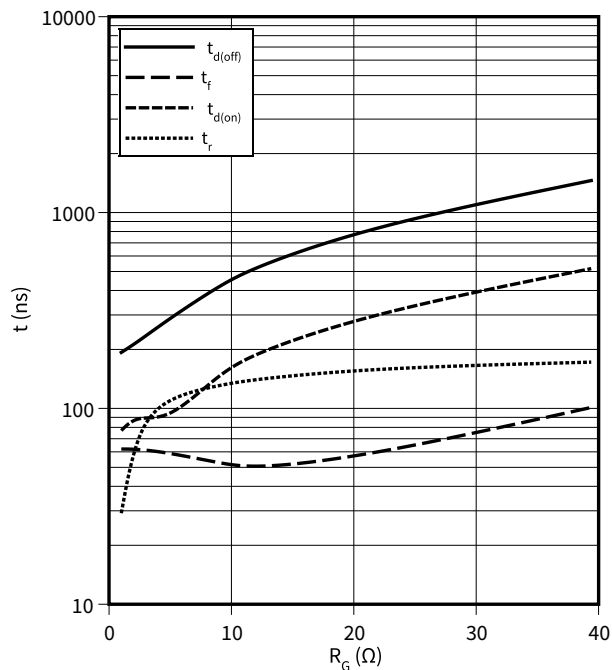
$$R_{Goff} = 5 \Omega, V_{CE} = 25 \text{ V}, T_{vj} = 175 \text{ °C}, V_{GE} = -8/15 \text{ V}, R_{Gon} = 5 \Omega$$



Typical switching times as a function of gate resistor, IGBT

$$t = f(R_G)$$

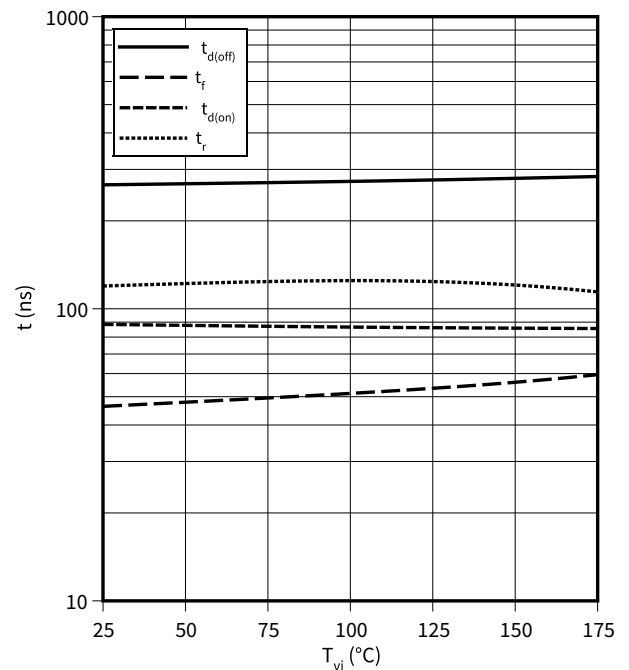
$$I_C = 200 \text{ A}, V_{CE} = 470 \text{ V}, T_{vj} = 175 \text{ °C}, V_{GE} = -8/15 \text{ V}$$



Typical switching times as a function of junction temperature, IGBT

$$t = f(T_{vj})$$

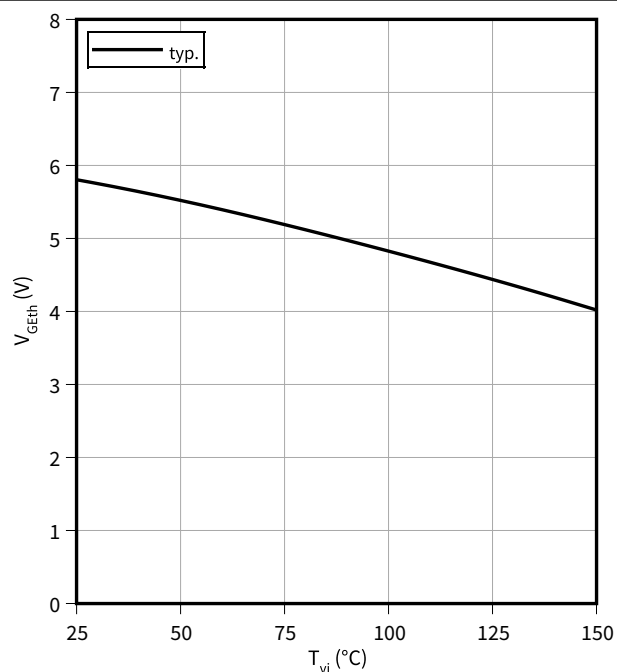
$$I_C = 200 \text{ A}, R_{Goff} = 5.0 \Omega, V_{CE} = 470 \text{ V}, V_{GE} = -8/15 \text{ V}, R_{Gon} = 5 \Omega$$



Typical Gate-emitter threshold voltage as a function of junction temperature, IGBT

$$V_{GEth} = f(T_{vj})$$

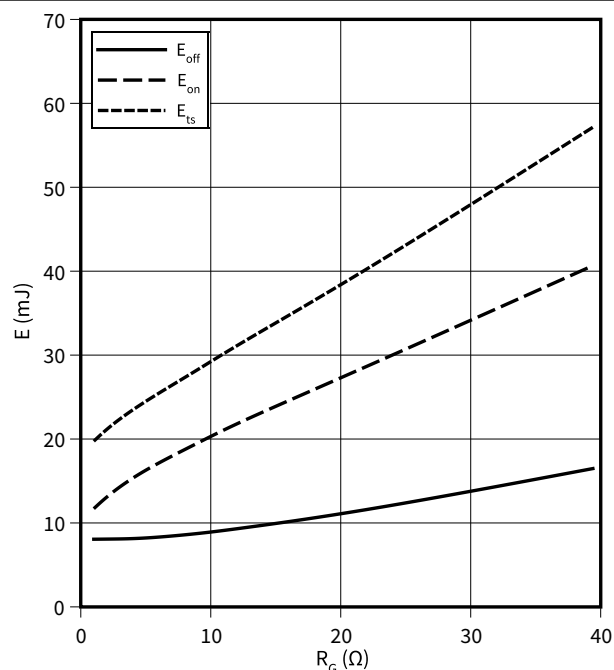
$$I_C = 2.60 \text{ mA}$$



Typical switching energy losses as a function of gate resistor, IGBT

$$E = f(R_G)$$

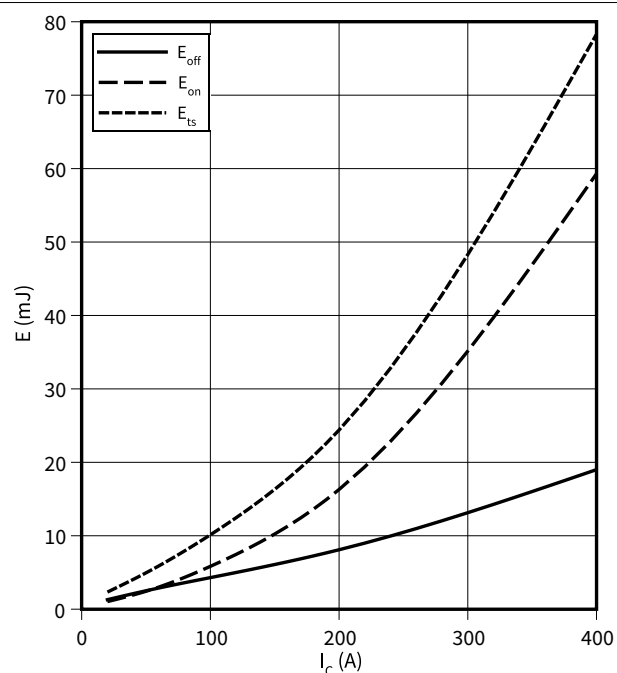
$$I_C = 200 \text{ A}, V_{CE} = 25 \text{ V}, T_{vj} = 175 \text{ °C}, V_{GE} = -8/15 \text{ V}$$



Typical switching energy losses as a function of collector current, IGBT

$$E = f(I_C)$$

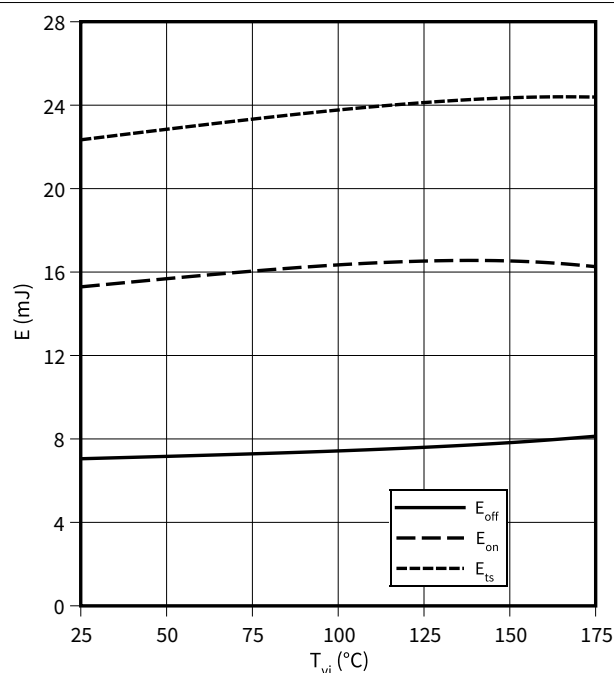
$$R_{Goff} = 5 \text{ Ω}, V_{CE} = 25 \text{ V}, T_{vj} = 175 \text{ °C}, V_{GE} = -8/15 \text{ V}, R_{Gon} = 5 \text{ Ω}$$



Typical switching energy losses as a function of junction temperature, IGBT

$$E = f(T_{vj})$$

$$I_C = 200 \text{ A}, R_{Goff} = 5.0 \text{ Ω}, V_{CE} = 470 \text{ V}, V_{GE} = -8/15 \text{ V}, R_{Gon} = 5 \text{ Ω}$$

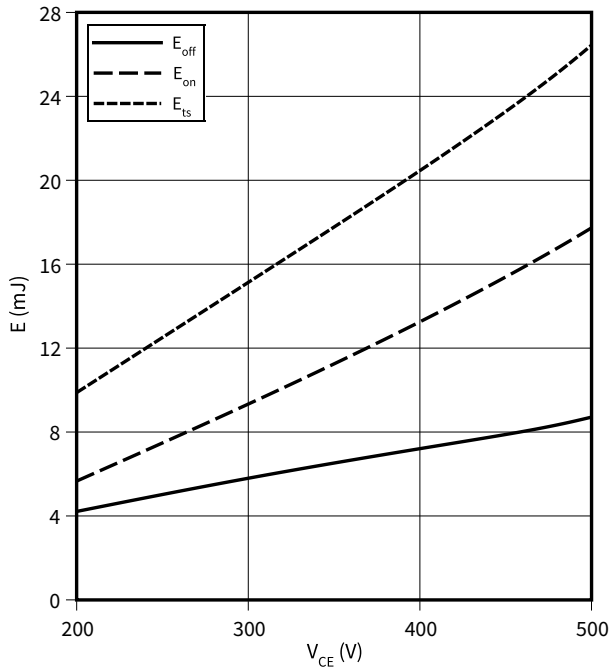


4 Characteristics diagrams

Typical switching energy losses as a function of collector emitter voltage, IGBT

$$E = f(V_{CE})$$

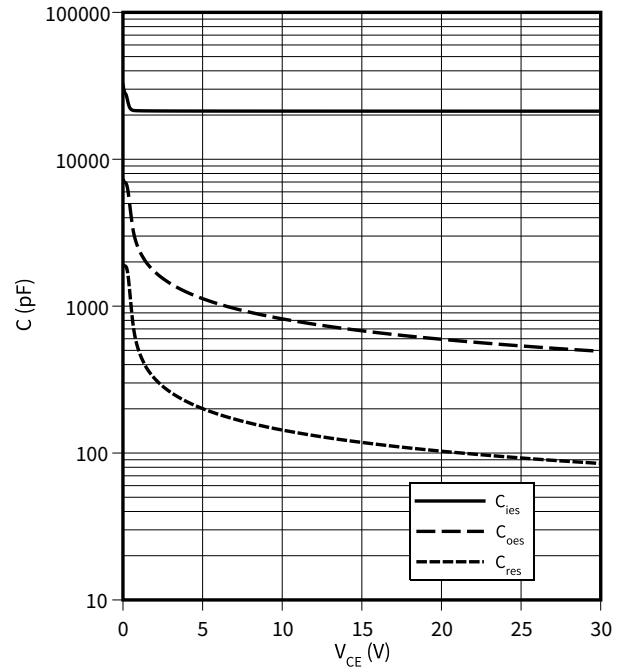
$I_C = 200 \text{ A}$, $R_{Goff} = 5 \Omega$, $T_{vj} \leq 175 \text{ }^\circ\text{C}$, $V_{GE} = -8/15 \text{ V}$, $R_{Gon} = 5 \Omega$



Typical capacitance as a function of collector-emitter voltage, IGBT

$$C = f(V_{CE})$$

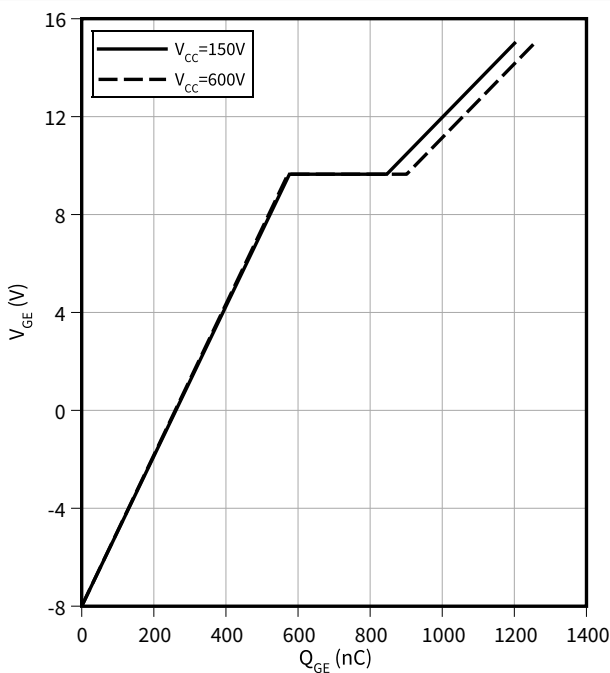
$f = 100 \text{ kHz}$, $V_{GE} = 0 \text{ V}$



Typical gate charge, IGBT

$$V_{GE} = f(Q_{GE})$$

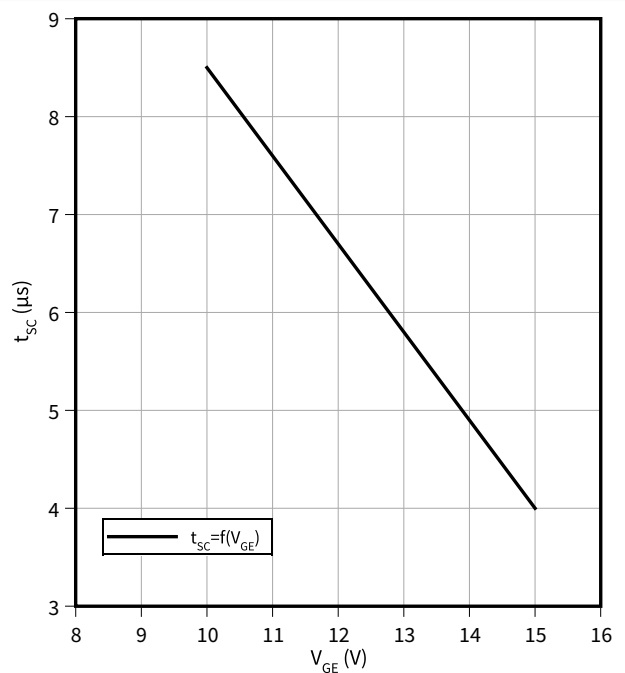
$I_C = 200 \text{ A}$



Typical Short circuit withstand time as a function of gate-emitter voltage, IGBT

$$t_{SC} = f(V_{GE})$$

$T_{vj} \leq 175 \text{ }^\circ\text{C}$, $V_{CC} \leq 470 \text{ V}$

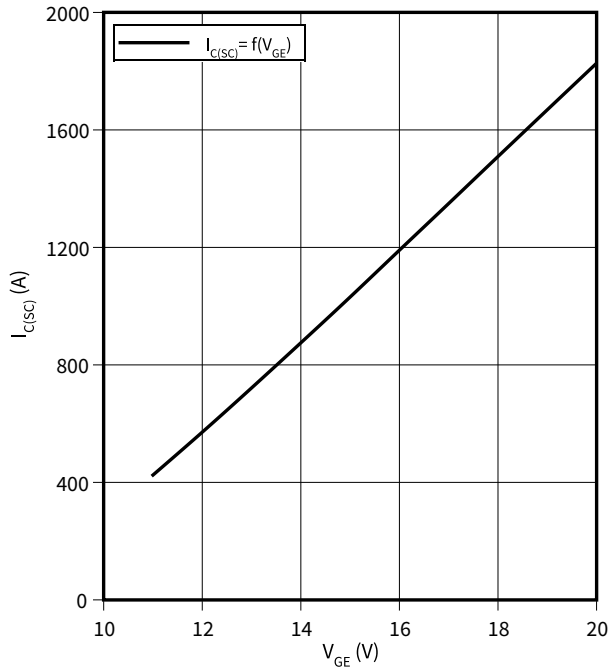


4 Characteristics diagrams

Typical short circuit collector current as a function of gate-emitter voltage, IGBT

$$I_{C(SC)} = f(V_{GE})$$

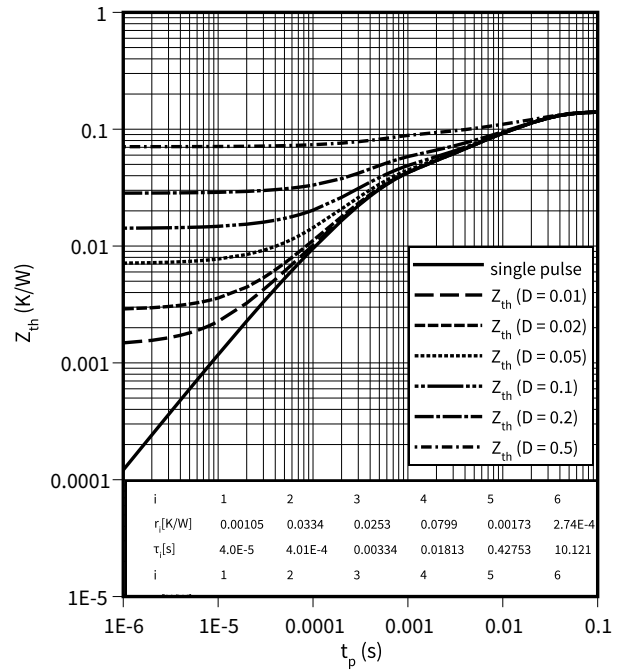
$T_{vj} \leq 175\text{ }^{\circ}\text{C}$, $V_{CC} \leq 470\text{ V}$



IGBT transient thermal impedance as a function of pulse width, IGBT

$$Z_{th} = f(t_p)$$

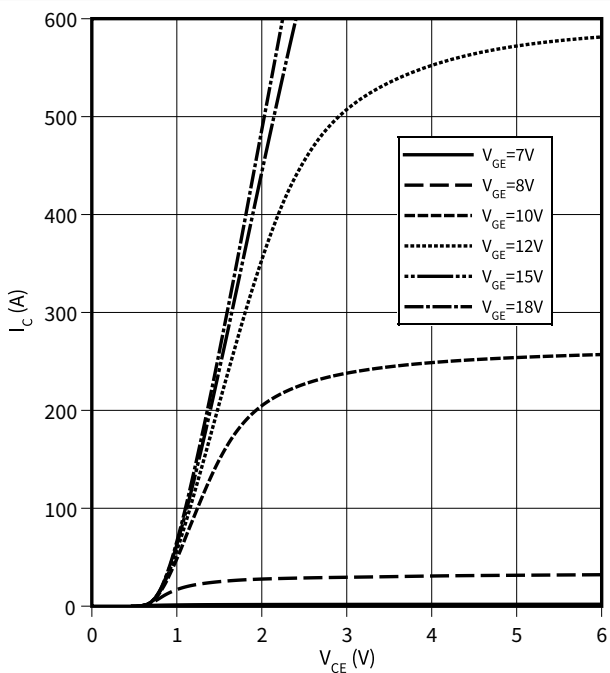
$$D = t_p/T$$



Typical output characteristic, IGBT

$$I_C = f(V_{CE})$$

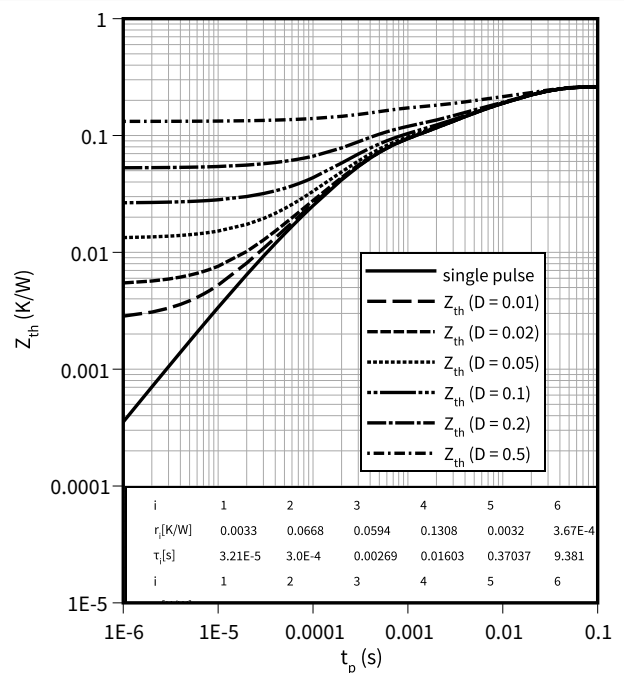
$T_{vj} = 25\text{ }^{\circ}\text{C}$



Diode transient thermal impedance as a function of pulse width, Diode

$$Z_{th} = f(t_p)$$

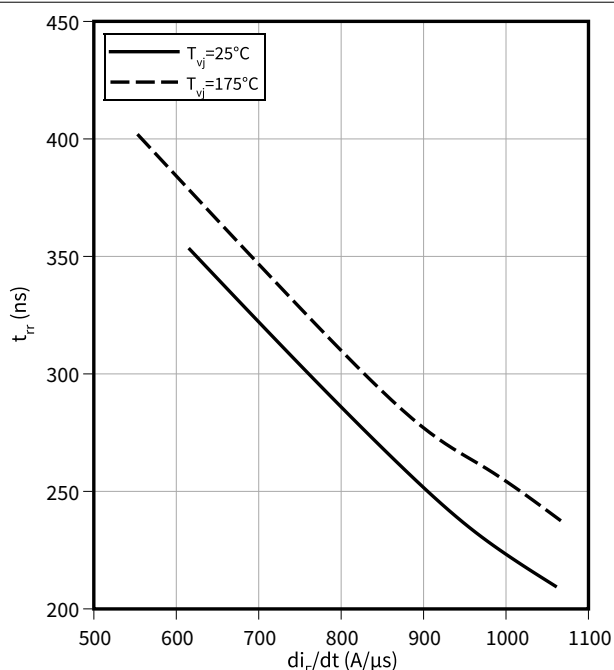
$$D = t_p/T$$



Typical reverse recovery time as a function of diode current slope, Diode

$$t_{rr} = f(di_F/dt)$$

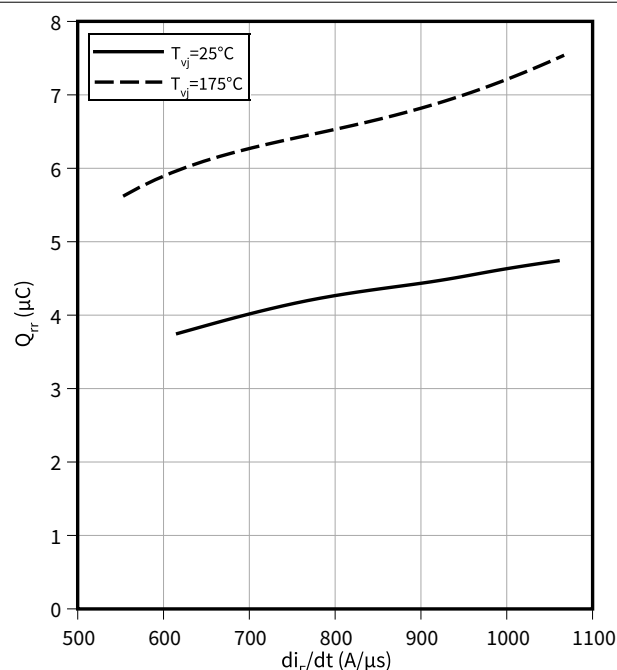
$V_R < 470 \text{ V}$, $I_F = 200 \text{ A}$



Typical reverse recovery charge as a function of diode current slope, Diode

$$Q_{rr} = f(di_F/dt)$$

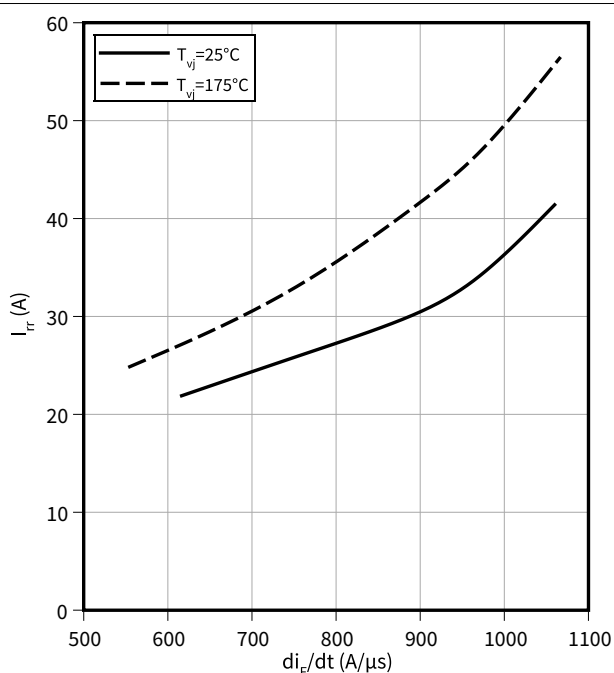
$V_R < 470 \text{ V}$, $I_F = 200 \text{ A}$



Typical reverse recovery current as a function of diode current slope, Diode

$$I_{rr} = f(di_F/dt)$$

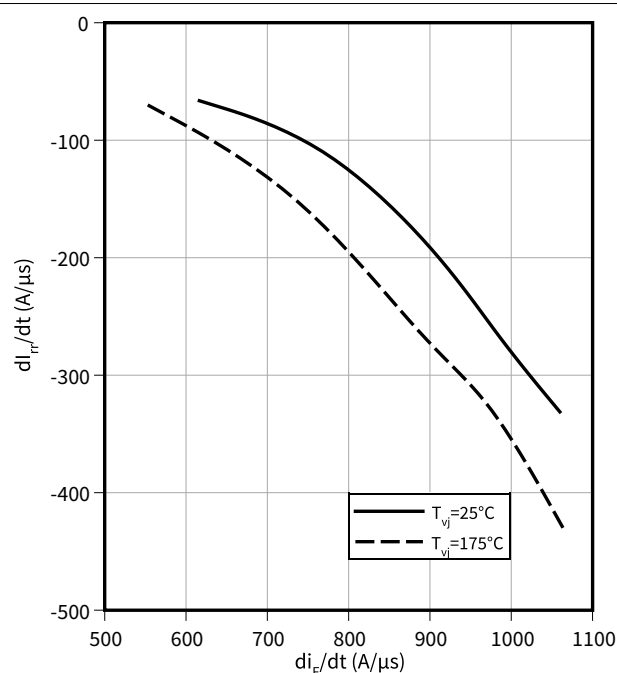
$V_R < 470 \text{ V}$, $I_F = 200 \text{ A}$



Typical diode peak rate of fall of reverse recovery current as a function of diode current slope, Diode

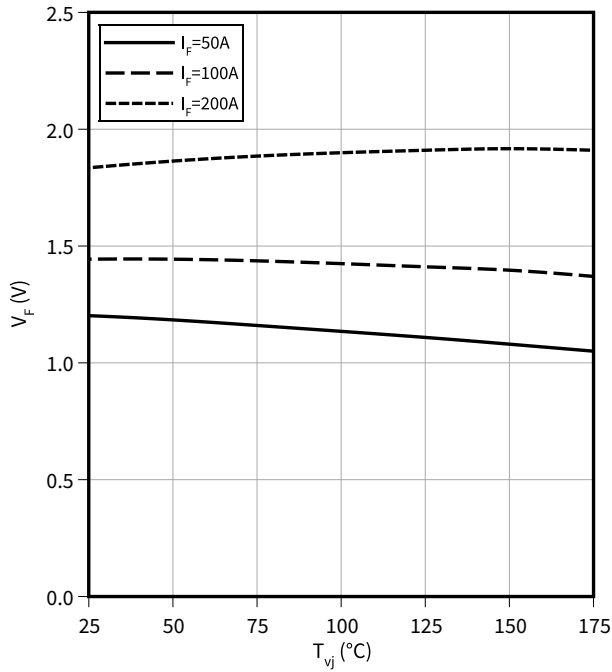
$$dI_{rr}/dt = f(di_F/dt)$$

$V_R < 470 \text{ V}$, $I_F = 200 \text{ A}$



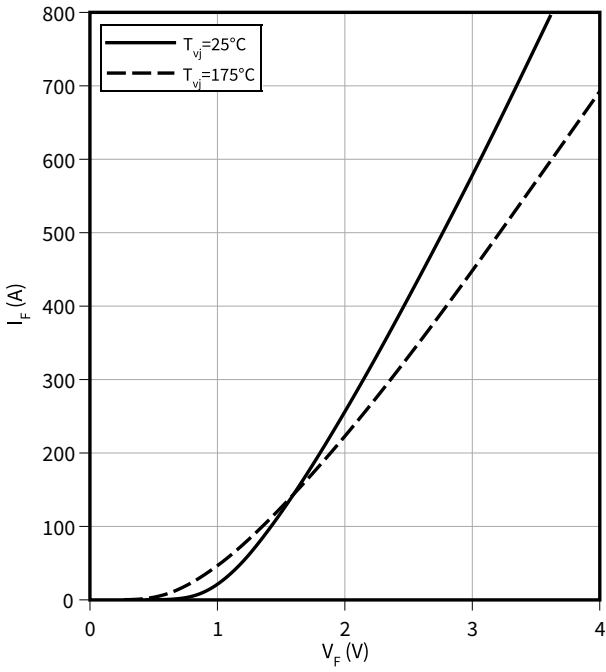
Typical diode forward voltage as a function of junction temperature, Diode

$V_F = f(T_{vj})$



Typical diode forward current as a function of forward voltage, Diode

$I_F = f(V_F)$



5 Package outlines

Package Drawing PG-TO247PLUS-3

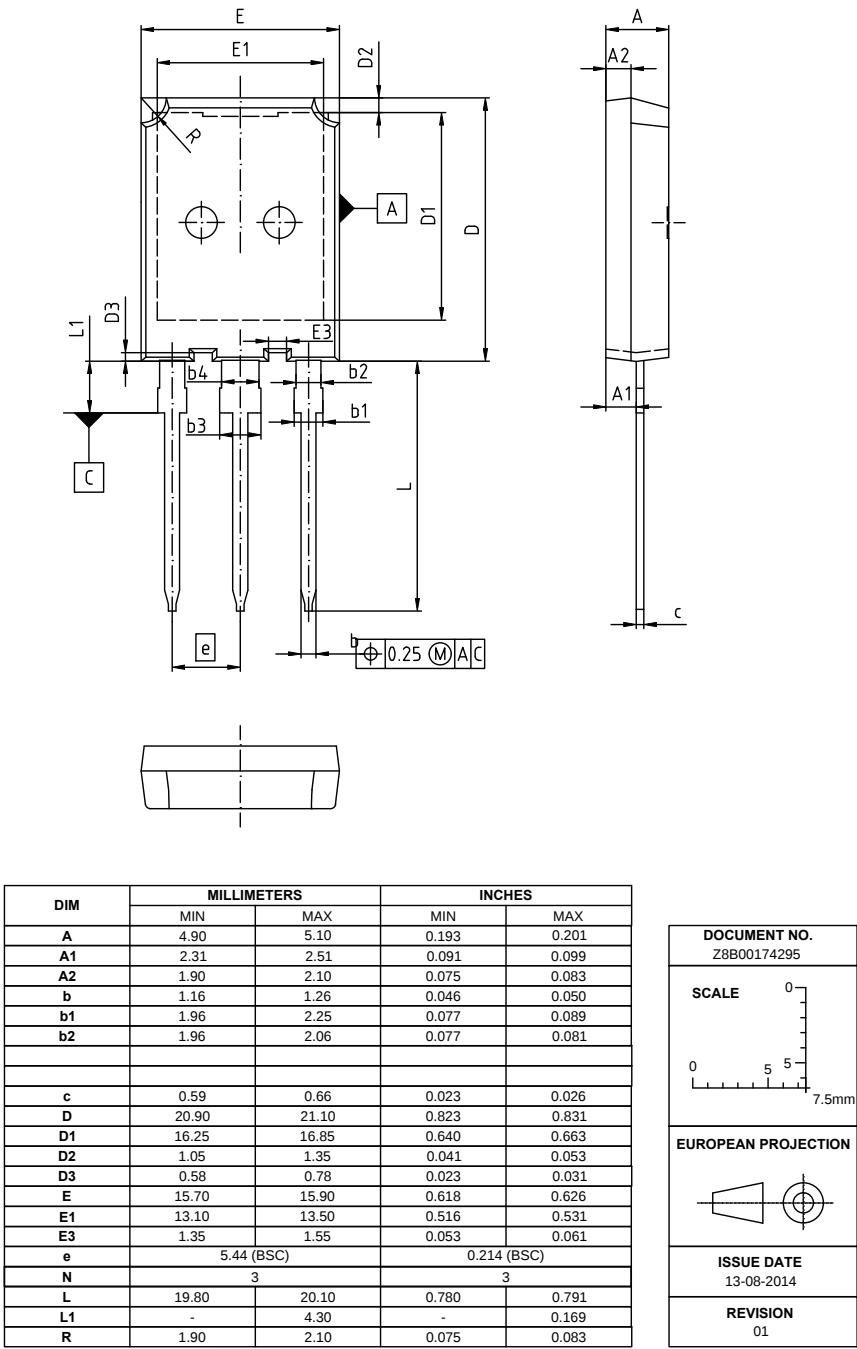


Figure 1

Revision history

Document revision	Date of release	Description of changes
V0.1	2020-10-09	Target
V0.2	2020-11-02	Updated marking on page1
V0.1		Target
n/a	2020-11-30	Datasheet migrated to a new system with a new layout and new revision number schema: target or preliminary datasheet = 0.xy; final datasheet = 1.xy
1.00	2022-02-16	Final datasheet
1.10	2022-03-16	Updated Isc and Rthjc

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